



Click [here](#) for the 3D model.

### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 0805             |
| L         | 2mm +/-0.2mm     |
| W         | 1.25mm +/-0.2mm  |
| T         | 0.78mm +/-0.10mm |
| S         | 0.75mm MIN       |
| B         | 0.5mm +/-0.25mm  |

### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000                   |

### General Information

|                          |  |
|--------------------------|--|
| Series                   | SMD Comm COG                               |
| Style                    | SMD Chip                                   |
| Description              | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features                 | Ultra-Stable, Low Loss, Class I            |
| RoHS                     | Yes  |
| Termination              | Tin  |
| Marking                  | No   |
| AEC-Q200                 | No   |
| Typical Component Weight | 11 mg                                      |
| Shelf Life               | 78 Weeks                                   |
| MSL                      | 1  |

### Specifications

|  |                           |
|--|---------------------------|
| Capacitance  | 33 pF                     |
| Measurement Condition  | 1 MHz 1.0Vrms             |
| Capacitance Tolerance  | 1%                        |
| Voltage DC   | 50 VDC                    |
| Dielectric Withstanding Voltage                                    | 125 VDC                   |
| Temperature Range  | -55/+125°C                |
| Temperature Coefficient  | COG                       |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms        |
| Aging Rate   | 0% Loss/Decade Hour       |
| Insulation Resistance  | 100 GOhms                 |